



Material Content Data Sheet



Sales Product Name	SGD02N120	Issued	28. April 2021
MA#	MA000207618		
Package	PG-TO252-3-11	Weight*	365.33 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.530	0.69	0.69	6926	6926
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		177	
	non noble metal	iron	7439-89-6	0.215	0.06		589	
	non noble metal	copper	7440-50-8	215.017	58.87	58.95	588549	589315
wire	non noble metal	aluminium	7429-90-5	0.615	0.17	0.17	1684	1684
encapsulation	organic material	carbon black	1333-86-4	1.215	0.33		3325	
	inorganic material	antimonytrioxide	1309-64-4	2.430	0.66		6650	
	plastics	brominated resin	-	2.430	0.66		6650	
	plastics	epoxy resin	-	24.296	6.65		66503	
	inorganic material	silicondioxide	60676-86-0	91.110	24.94	33.24	249388	332516
leadfinish	non noble metal	tin	7440-31-5	3.740	1.02	1.02	10237	10237
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	249	250
solder	non noble metal	tin	7440-31-5	0.048	0.01		130	
	noble metal	silver	7440-22-4	0.059	0.02		163	
	non noble metal	lead	7439-92-1	2.271	0.62	0.65	6217	6510
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			16	
	non noble metal	iron	7439-89-6	0.019	0.01		53	
	non noble metal	copper	7440-50-8	19.177	5.25	5.26	52493	52562
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com